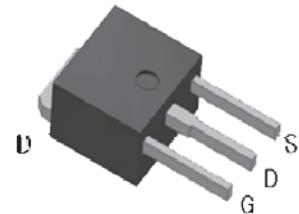
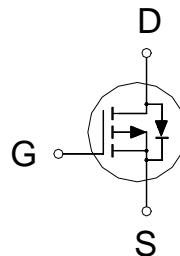


**P-Channel Logic Level Enhancement Mode Field Effect Transistor**

**Product Summary:**

BV <sub>DSS</sub>	-30V
R <sub>DSON</sub> (MAX.)	6.8mΩ
I <sub>D</sub>	-80A



UIS, Rg 100% Tested

Pb-Free Lead Plating & Halogen Free



**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V <sub>GS</sub>	±25	V
Continuous Drain Current	T <sub>C</sub> = 25 °C	I <sub>D</sub>	-80	A
	T <sub>C</sub> = 100 °C		-51	
Pulsed Drain Current <sup>1</sup>		I <sub>DM</sub>	-240	
Avalanche Current		I <sub>AS</sub>	-35	
Avalanche Energy	L = 0.1mH, I <sub>D</sub> =-35A, R <sub>G</sub> =25 Ω	E <sub>AS</sub>	61.25	mJ
Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	78	W
	T <sub>C</sub> = 100 °C		31	
Operating Junction & Storage Temperature Range		T <sub>j</sub> , T <sub>stg</sub>	-55 to 150	°C

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R <sub>θJC</sub>		1.6	°C / W
Junction-to-Ambient <sup>3</sup>	R <sub>θJA</sub>		62.5	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>Duty cycle ≤ 1%

**ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)**

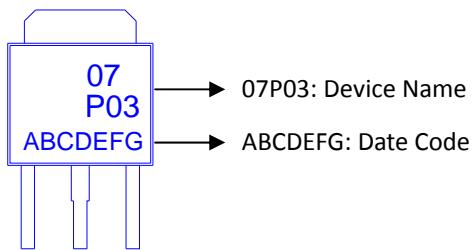
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = -250\mu\text{A}$	-30			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1	-1.5	-2	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -24V, V_{GS} = 0V$			-1	$\mu\text{A}$
		$V_{DS} = -20V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			-10	
On-State Drain Current <sup>1</sup>	$I_{D(\text{ON})}$	$V_{DS} = -5V, V_{GS} = -10V$	-80			A
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(\text{ON})}$	$V_{GS} = -10V, I_D = -24A$		5.5	6.8	$\text{m}\Omega$
		$V_{GS} = -4.5V, I_D = -15A$		8.5	11.5	
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = -5V, I_D = -24A$		24		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = -15V, f = 1\text{MHz}$		4294		$\text{pF}$
Output Capacitance	$C_{oss}$			634		
Reverse Transfer Capacitance	$C_{rss}$			566		
Gate Resistance	$R_g$	$V_{GS} = 15\text{mV}, V_{DS} = 0V, f = 1\text{MHz}$		3.0		$\Omega$
Total Gate Charge <sup>1,2</sup>	$Q_g$	$V_{DS} = -15V, V_{GS} = -10V, I_D = -25A$		62.4		$\text{nC}$
Gate-Source Charge <sup>1,2</sup>	$Q_{gs}$			8.5		
Gate-Drain Charge <sup>1,2</sup>	$Q_{gd}$			13		
Turn-On Delay Time <sup>1,2</sup>	$t_{d(\text{on})}$	$V_{DS} = -15V, I_D = -1A, V_{GS} = -10V, R_{GS} = 2.7\Omega$		18		$\text{nS}$
Rise Time <sup>1,2</sup>	$t_r$			26		
Turn-Off Delay Time <sup>1,2</sup>	$t_{d(\text{off})}$			22		
Fall Time <sup>1,2</sup>	$t_f$			75		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_c = 25^\circ\text{C}</math>)</b>						
Continuous Current	$I_s$				-30	$\text{A}$
Pulsed Current <sup>3</sup>	$I_{SM}$				-120	
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = -24A, V_{GS} = 0V$			-1.2	V
Reverse Recovery Time	$t_{rr}$	$I_F = I_s, dI_F/dt = 100A / \mu\text{s}$		52		$\text{nS}$
Reverse Recovery Charge	$Q_{rr}$			60		$\text{nC}$

<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .<sup>2</sup>Independent of operating temperature.

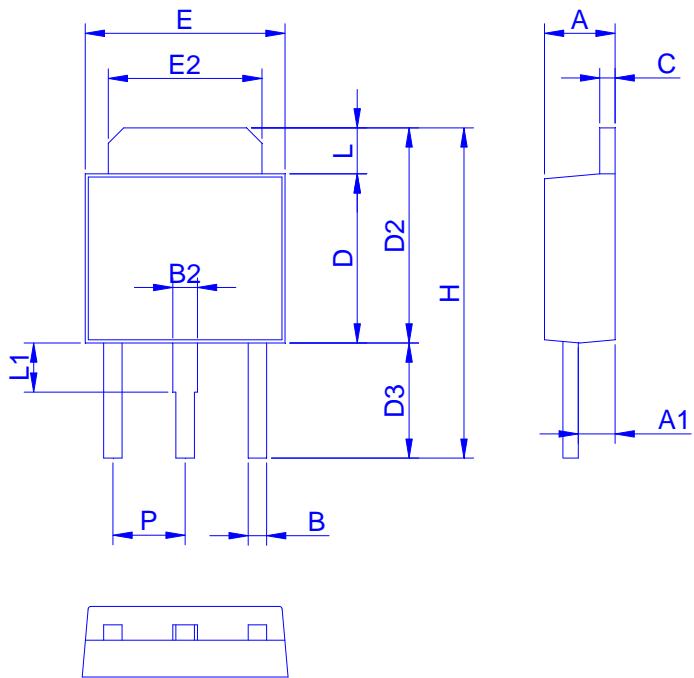
<sup>3</sup>Pulse width limited by maximum junction temperature.

#### Ordering & Marking Information:

Device Name: LB07P03E for IPAK (TO-251)



#### Outline Drawing



#### Dimension in mm

Dimension	A	A1	B	B2	C	D	D2	D3	E	E2	H	L	L1	P
Min.	2.10	0.90	0.40	0.60	0.40	5.30	6.70	3.40	6.30	4.80	10.2	0.89	0.90	2.10
Max.	2.50	1.50	0.90	1.15	0.60	6.25	7.30	4.30	6.80	5.50	11.5	1.40	1.80	2.50

